ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and P	<b>position Dee</b> IPC, Bannockt an-American co	claration ourn, Illinois. A opyright conve	All rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the substance of	ces within the manu wer level materials	facturer listed for which the	d item. Note: i e manufacture	if the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Aaterials and	ials and Mfg Information			
upplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2023-06-08			
Contact Name Title - Contact			ct	Phone - Contact*				Emai	Email - Contact*				
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - R			itle - Representative			Phone - Representative*			Email	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr 1		em Number Mfr Item Name				Effective Date			ite	Weight*	UOM	Unit Type	
	L78LR0:	L78LR05EL-TR-E Linear regu		lator		2023-06-08				350.0	mg	Each	
Ianufacturing Proccess Inform	ation						-						
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Bas		Alloy J-STD-020 MSL Rati		L Rating	Peak Proce	Peak Process Body Temperature Max Time at		Peak Tempe	k Temperature Number of Reflow Cycles			
contains Bi		CU Alloy NA			0	0 C 30		sec	seconds 3				
omments													
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.26	mg	Supplier	Silicon (Si)	7440-21-3		2.2516	mg
			Supplier	Polyimide	Proprietary Data		0.0084	mg
Die Attach	0.64	mg	Supplier	Silver (Ag)	7440-22-4		0.0192	mg
			А	Lead (Pb)	7439-92-1	7a	0.6016	mg
			Supplier	Tin (Sn)	7440-31-5		0.0128	mg
			Supplier	Copper (Cu)	7440-50-8		0.0064	mg
Lead Frame	200.55	mg	Supplier	Tin (Sn)	7440-31-5		0.2808	mg
			Supplier	Copper (Cu)	7440-50-8		200.2692	mg
Mold Compound-Black	139.34	mg		Brominated epoxy resin	proprietary data		1.8114	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		16.0241	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		2.7868	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6967	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.9094	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		103.1116	mg
Plating	7.08	mg	В	Bismuth (Bi)	7440-69-9		0.0425	mg
			Supplier	Tin (Sn)	7440-31-5		7.0375	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg